

FIG. 1

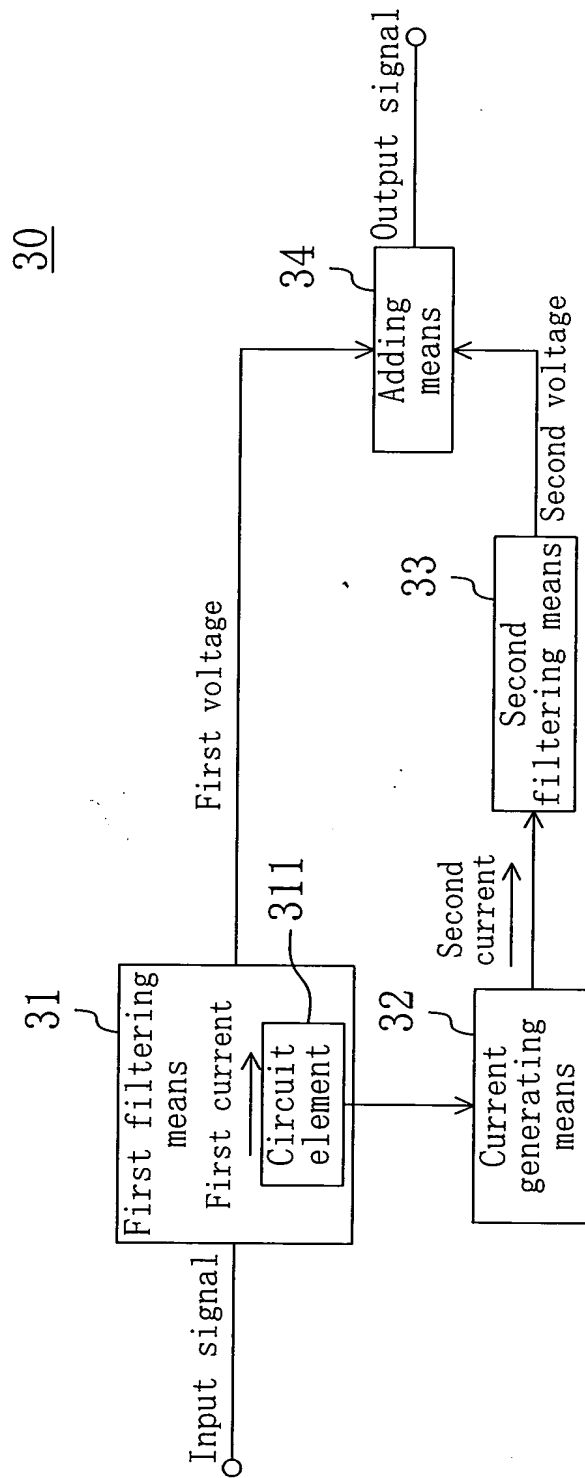


FIG. 2

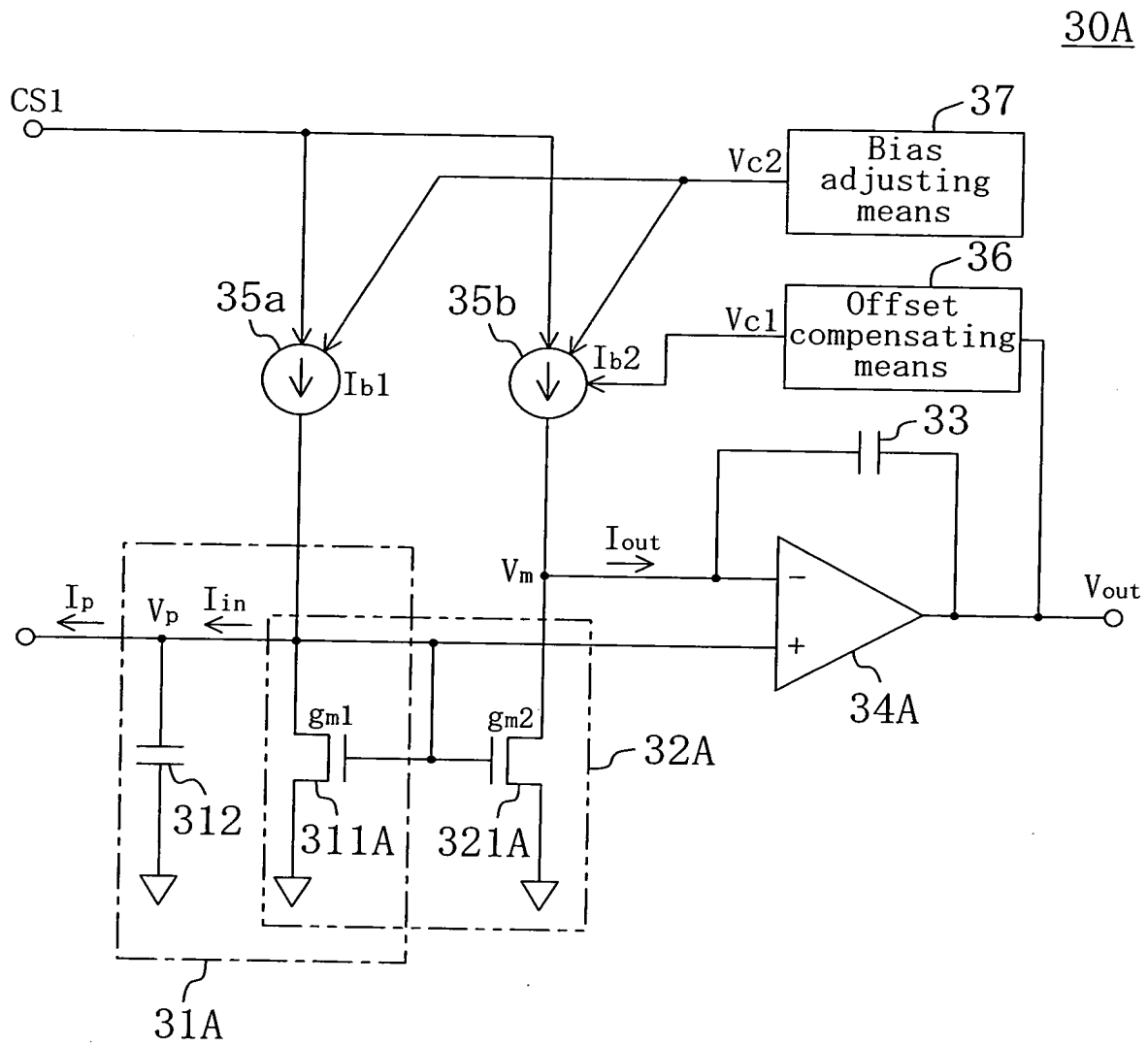


FIG. 3

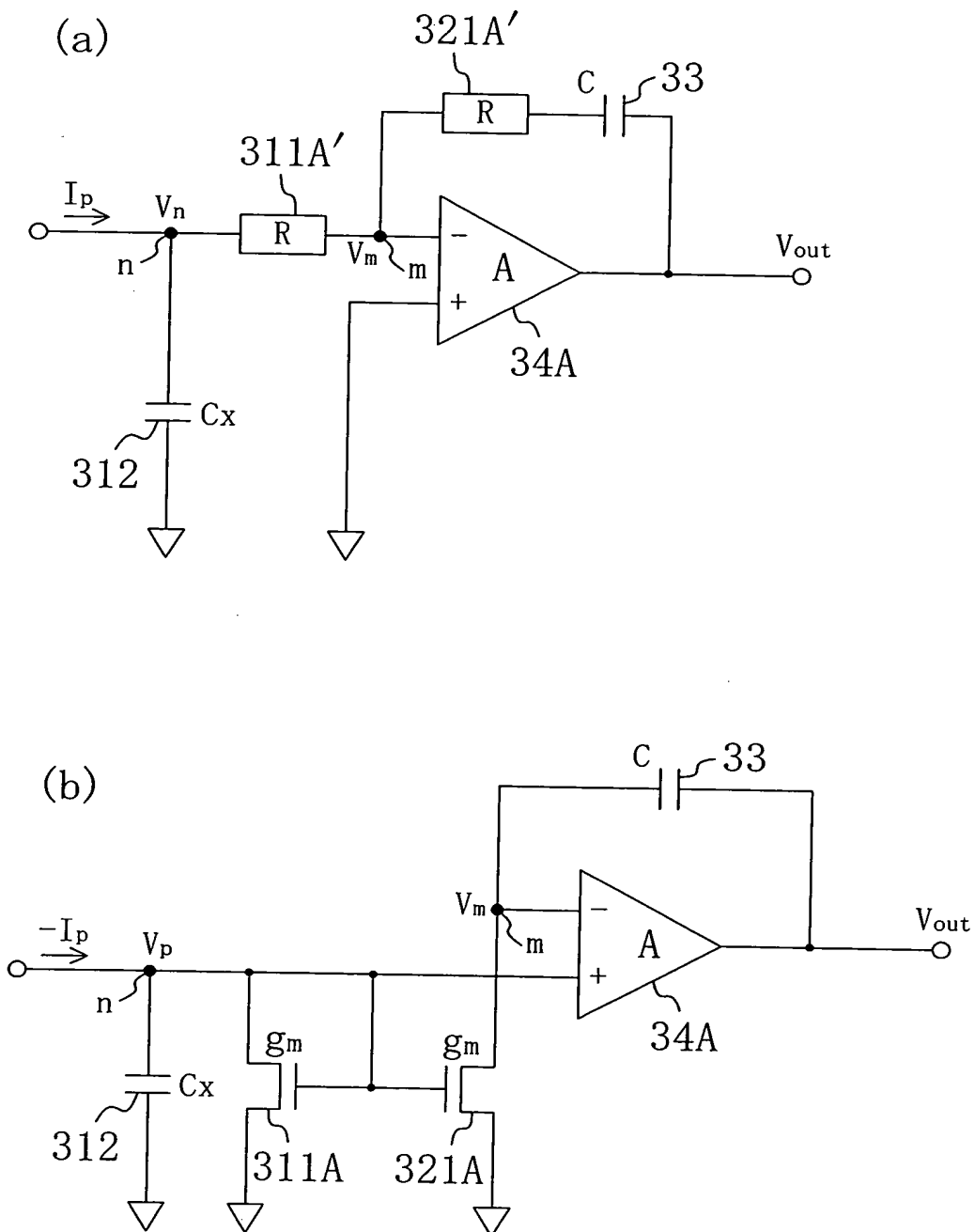


FIG. 4

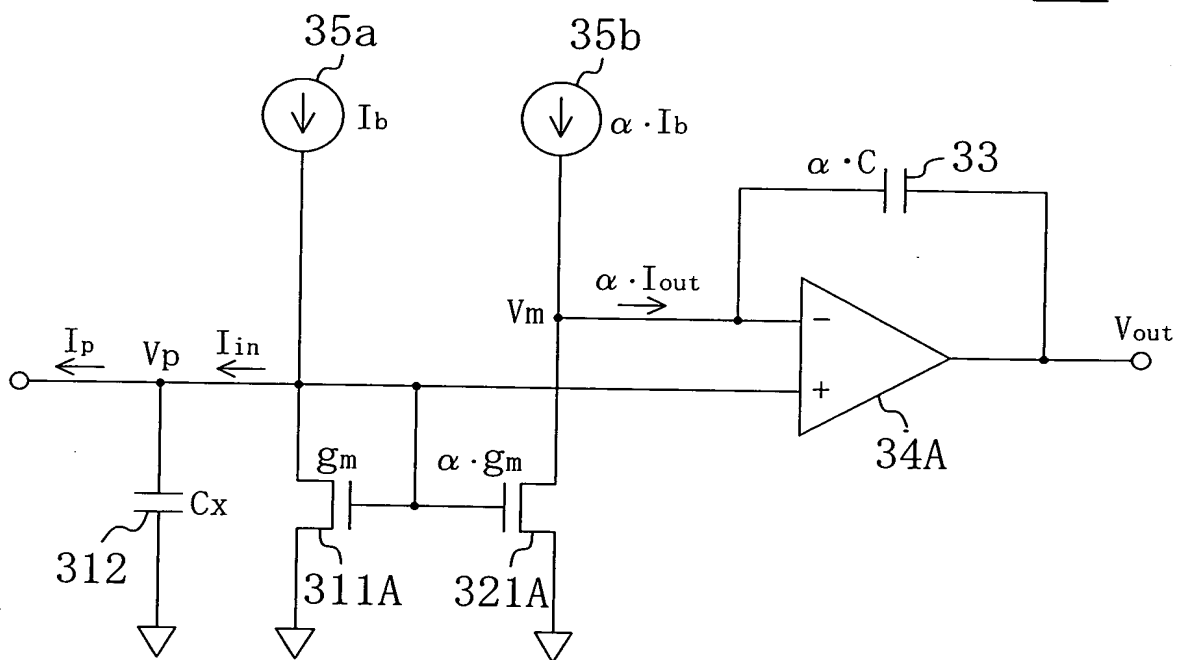
30A

FIG. 5

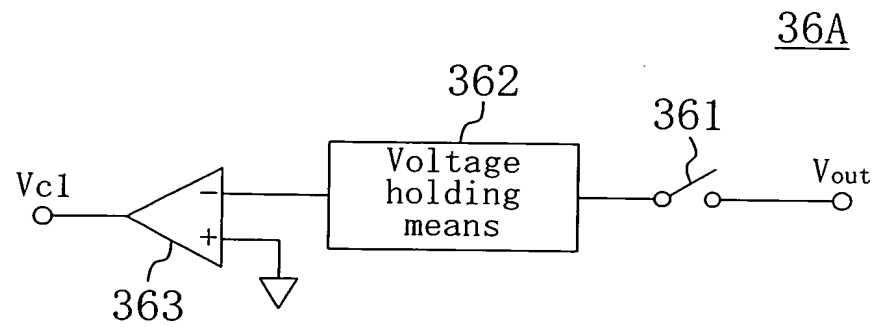


FIG. 6

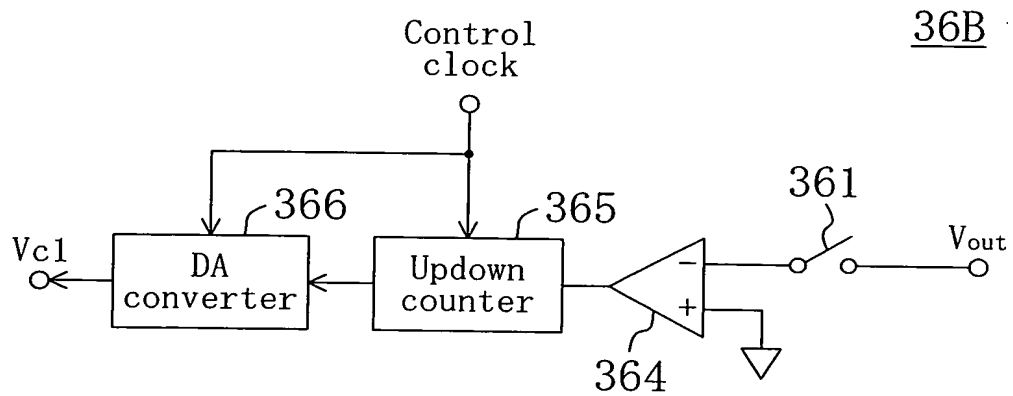


FIG. 7

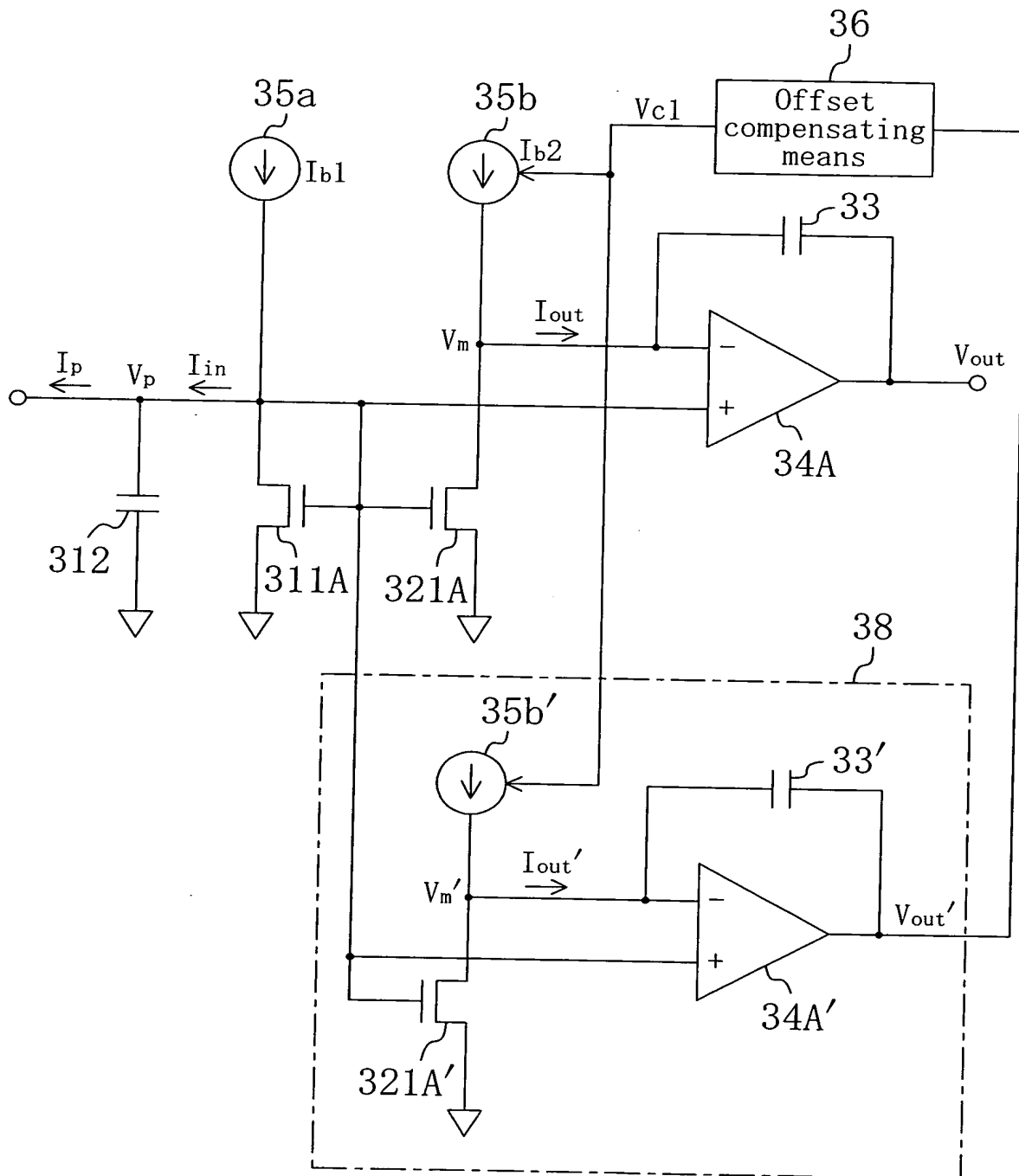


FIG. 8

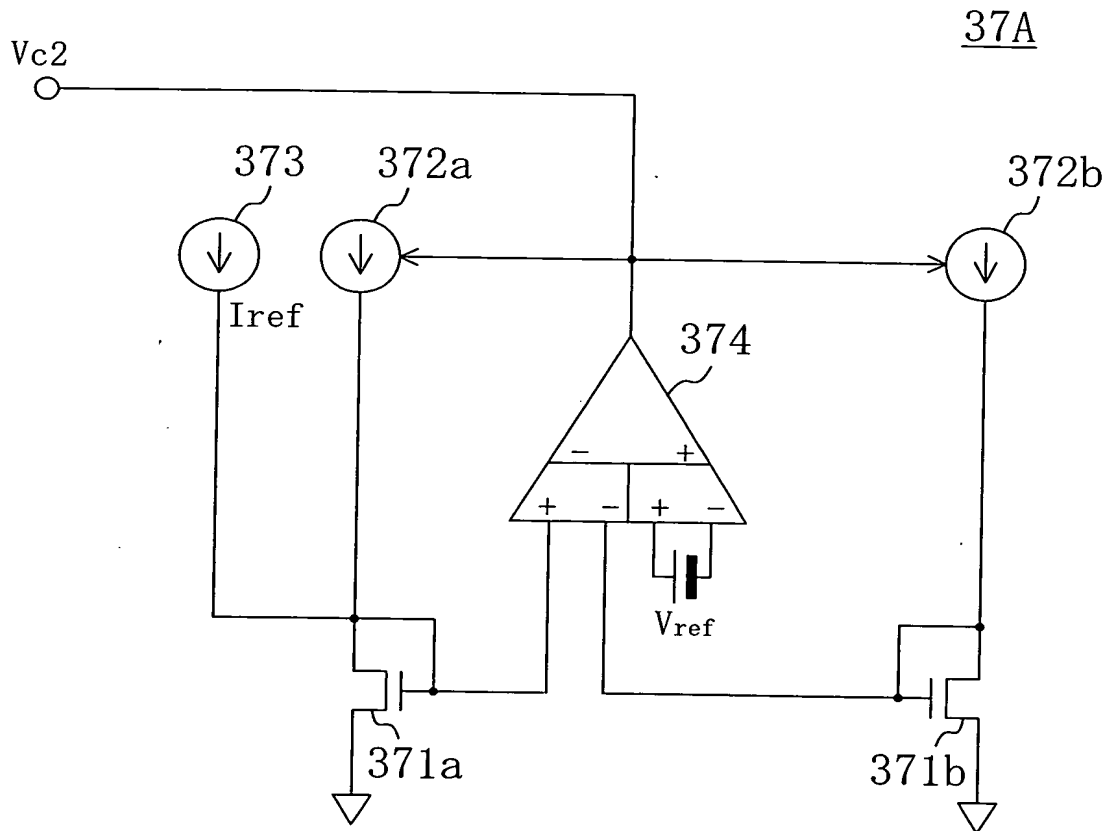


FIG. 9

37B

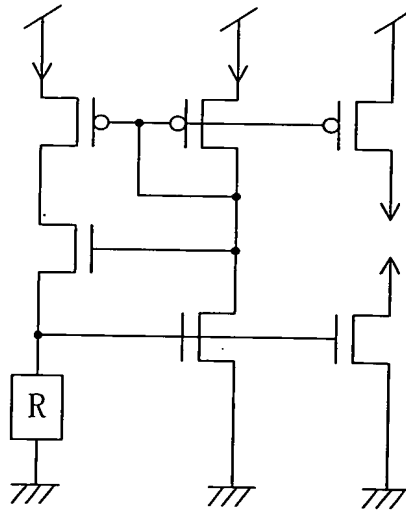




FIG. 10

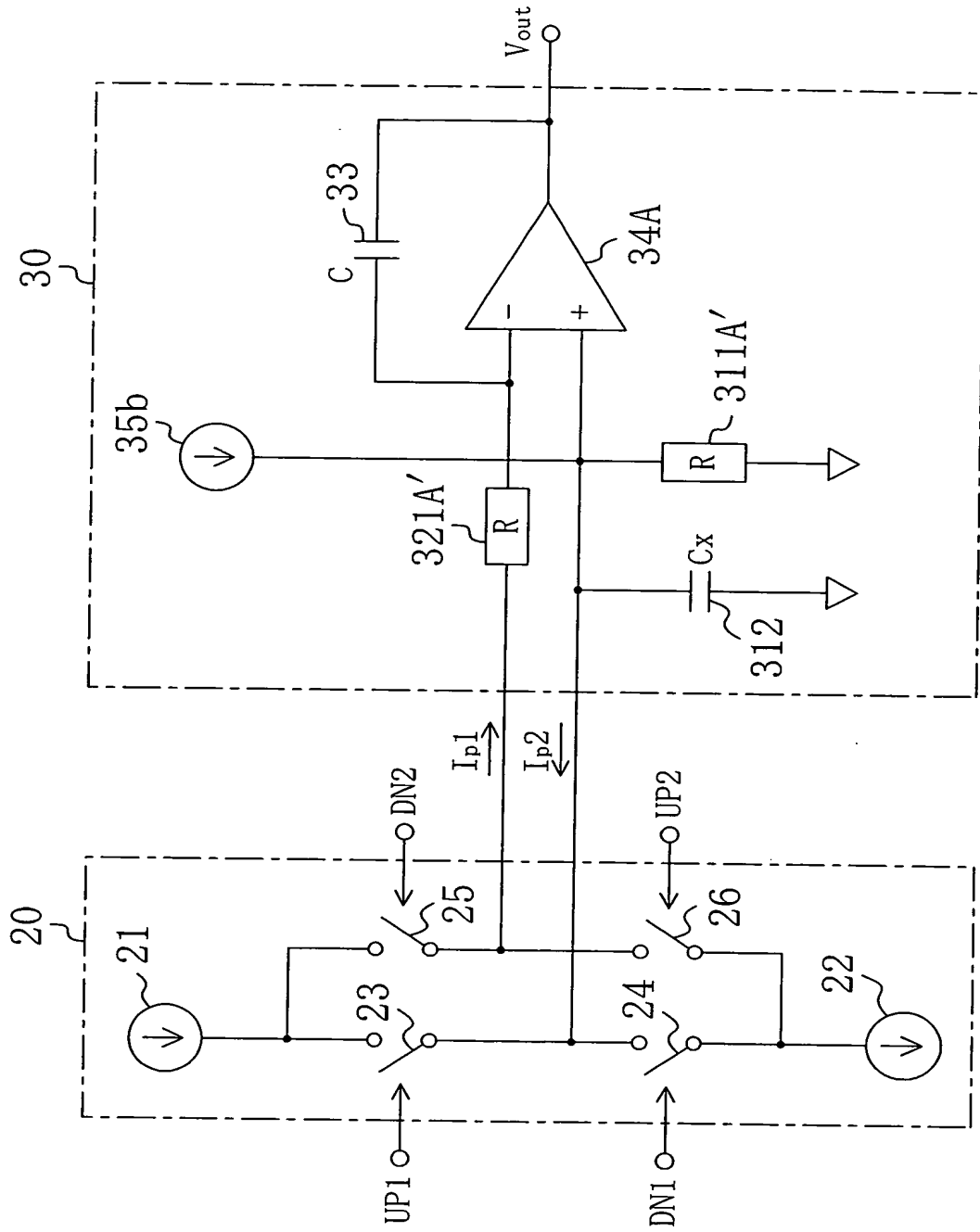


FIG. 11

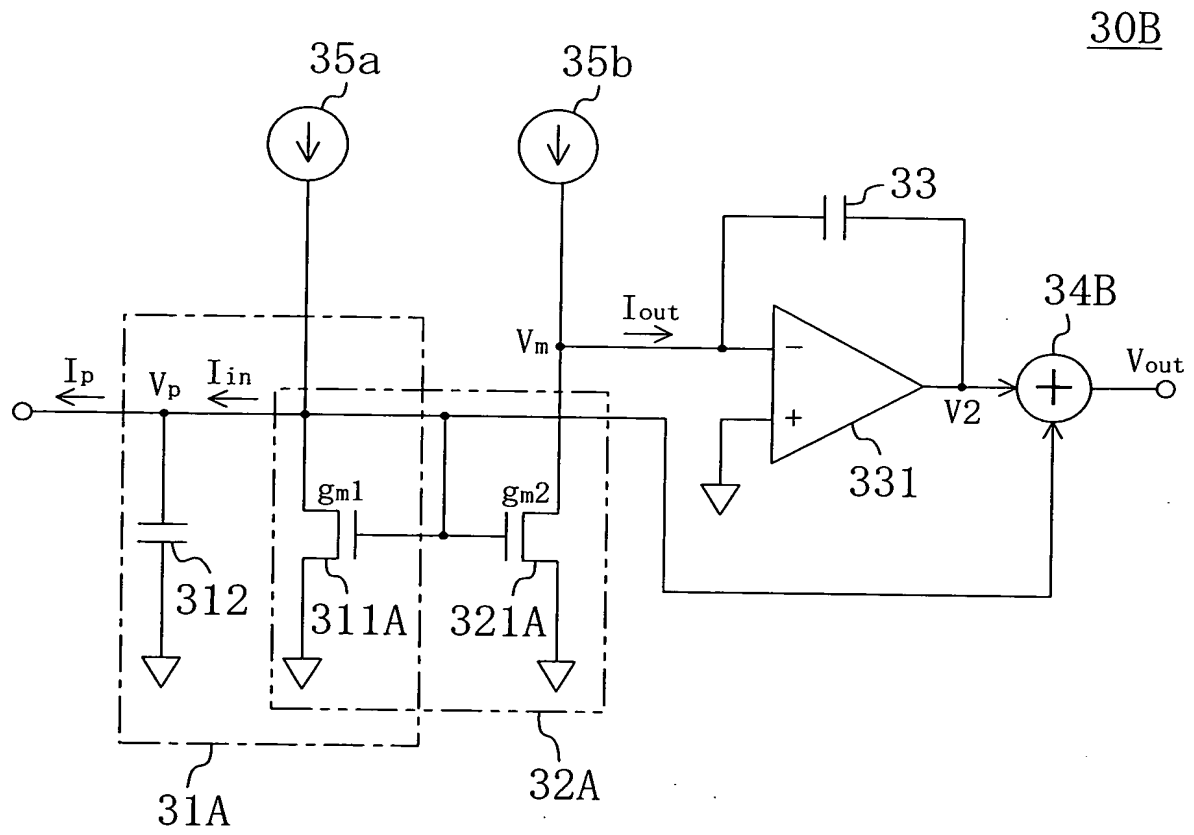


FIG. 12

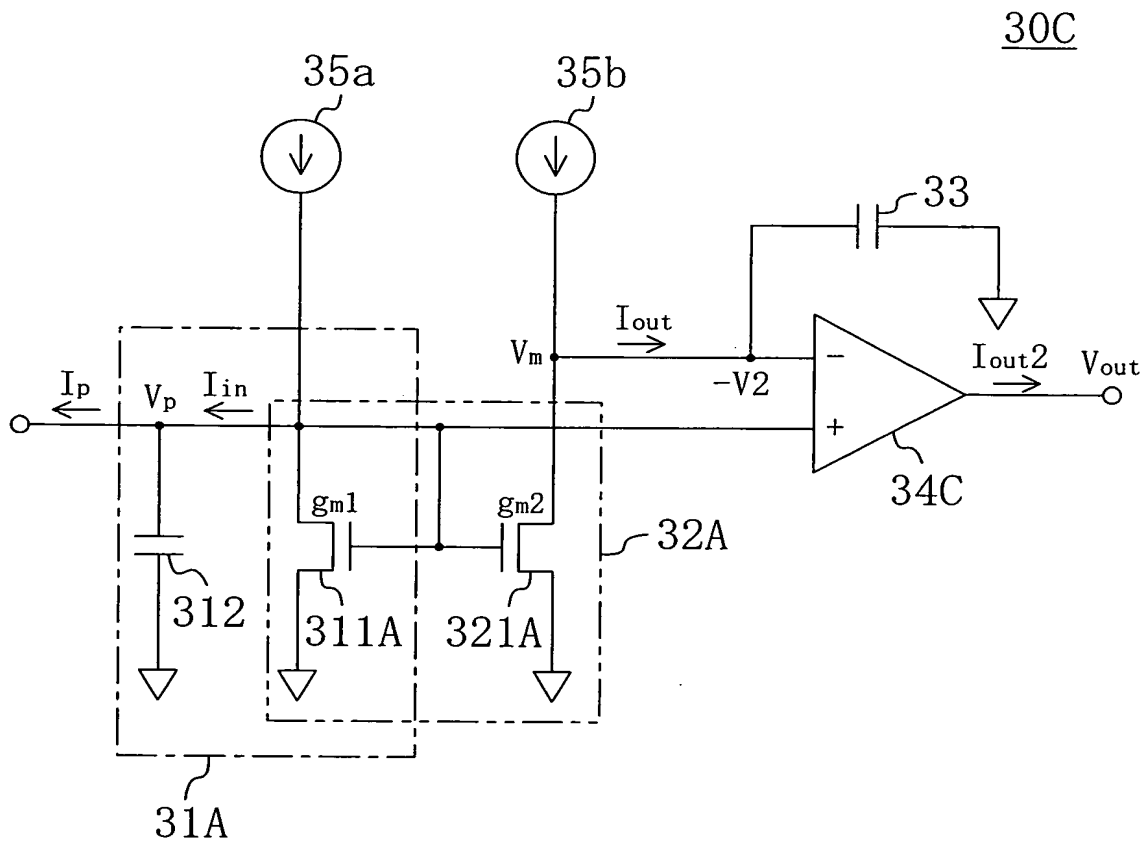
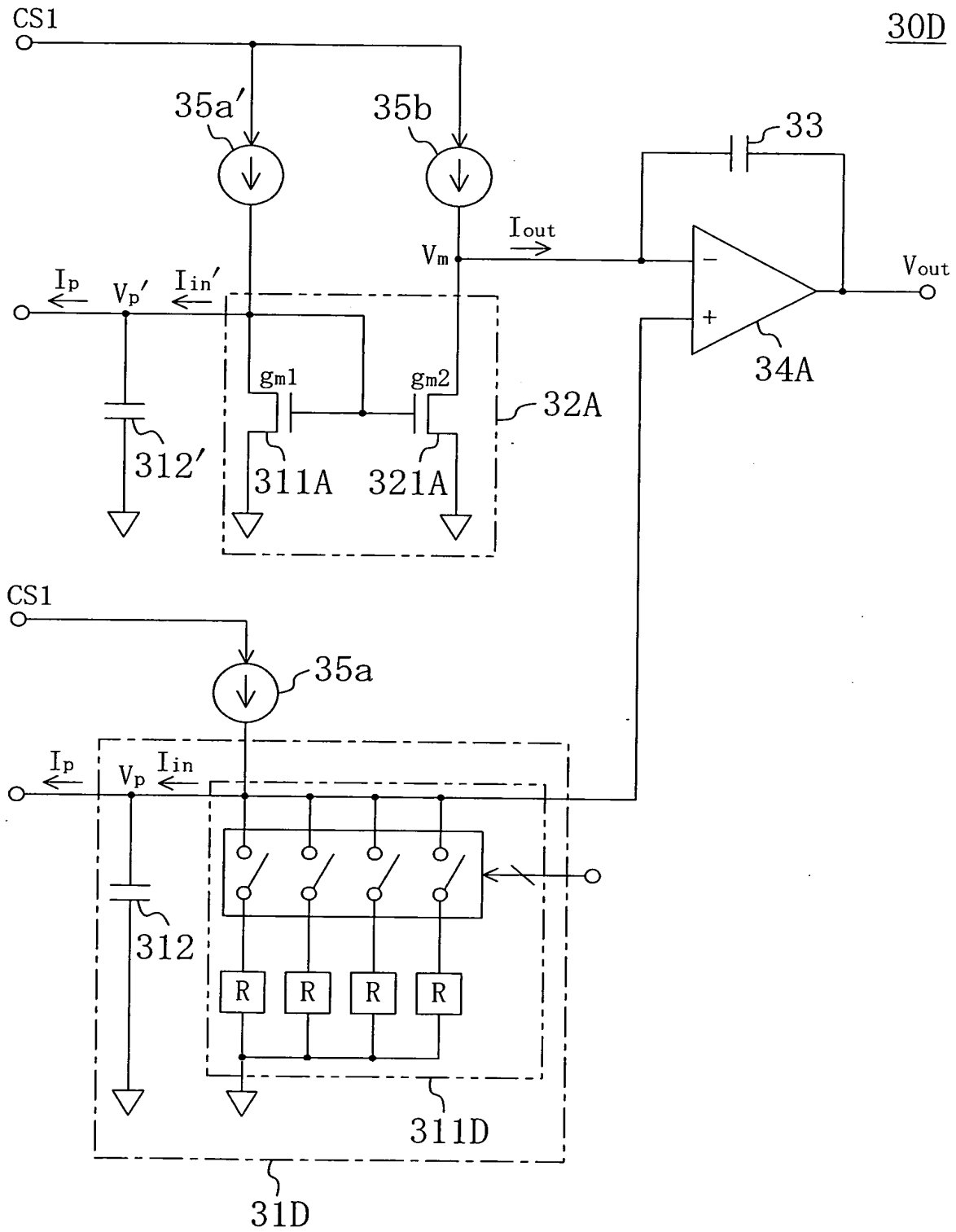


FIG. 13



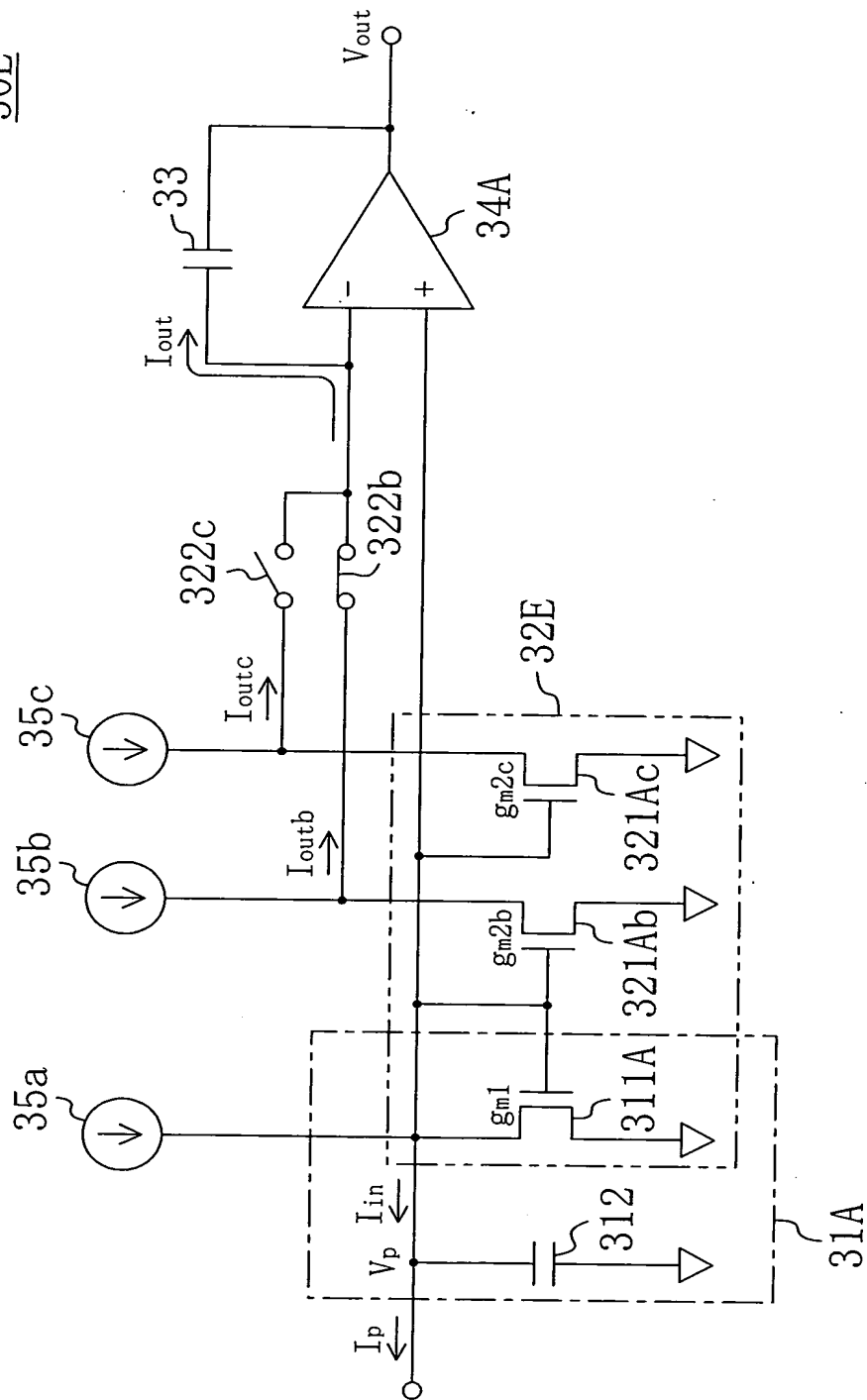
30E

FIG. 15

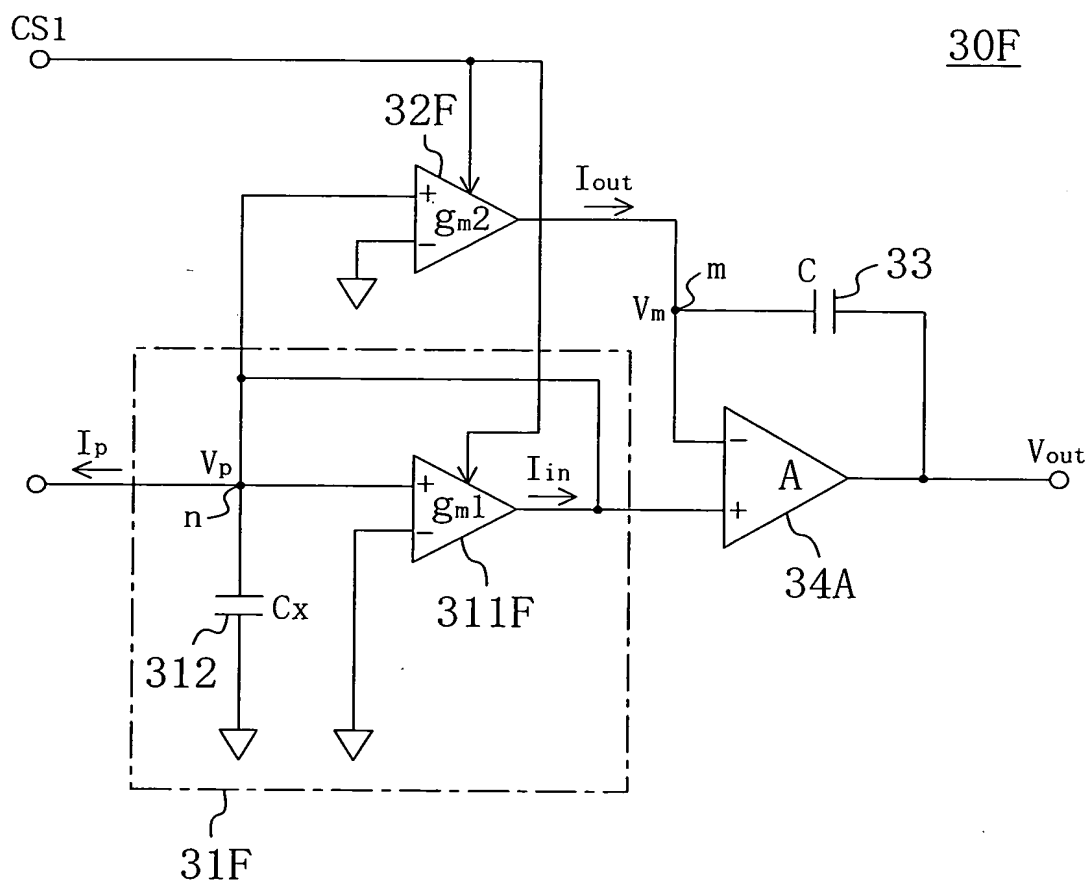


FIG. 16

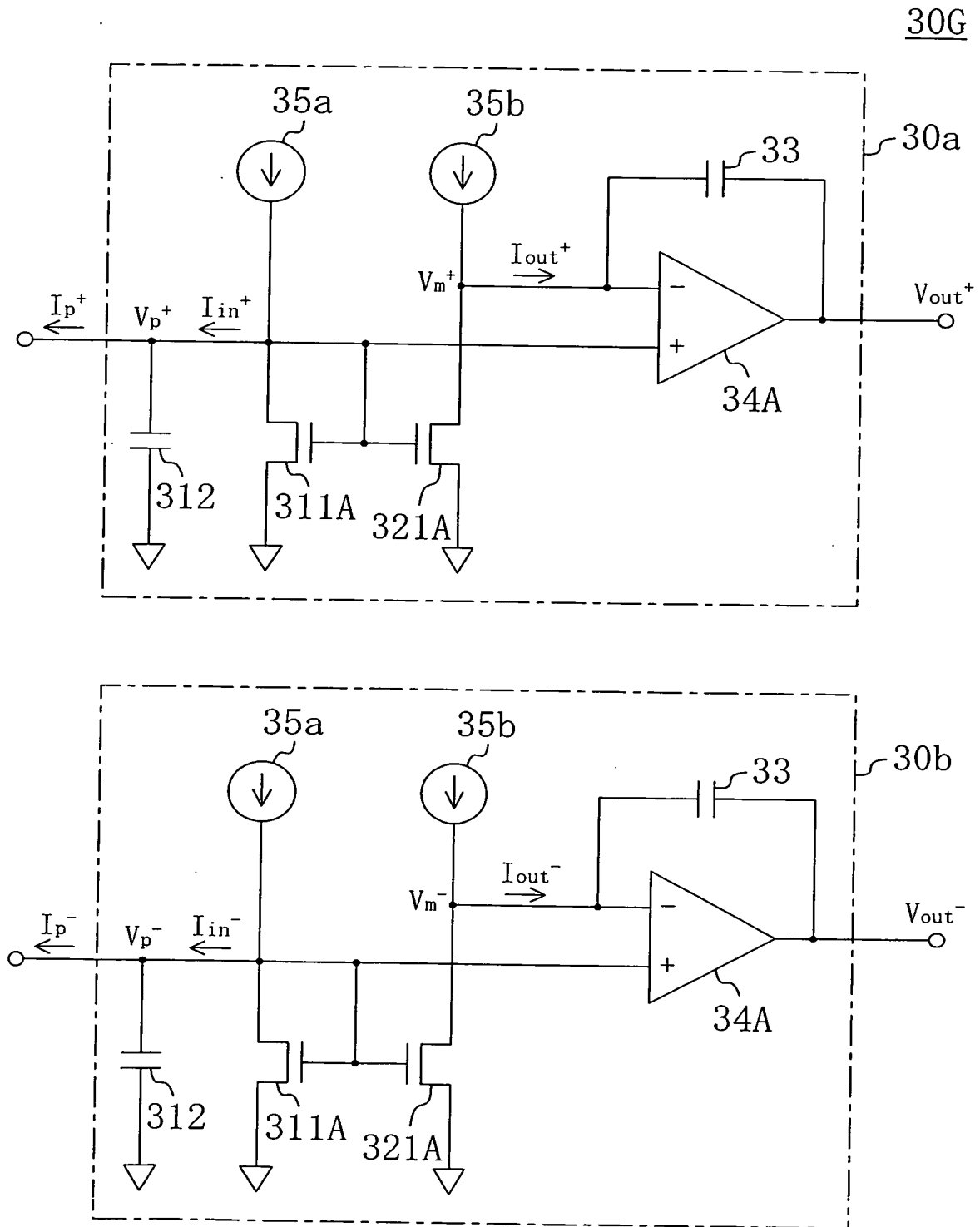


FIG. 17

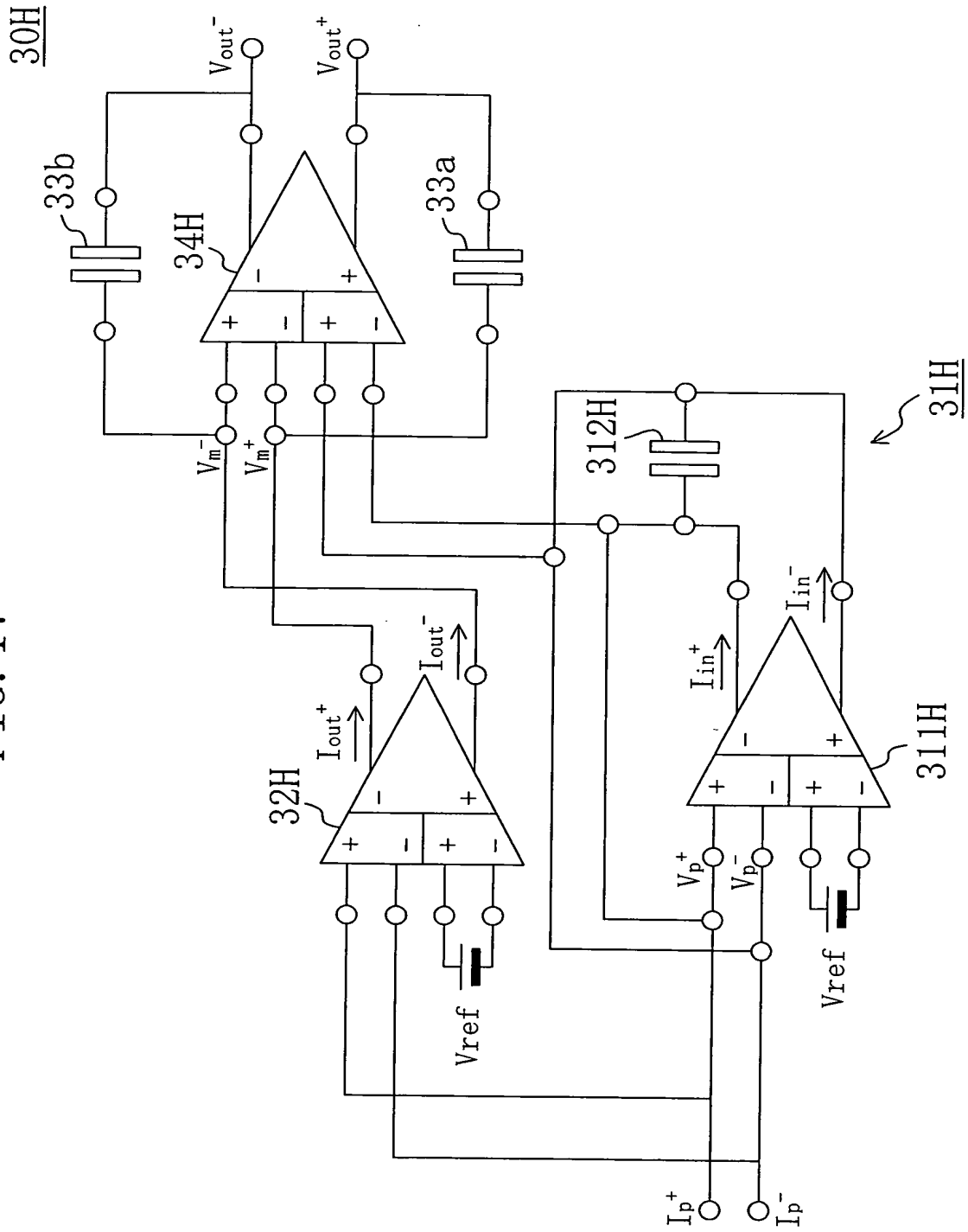




FIG. 18

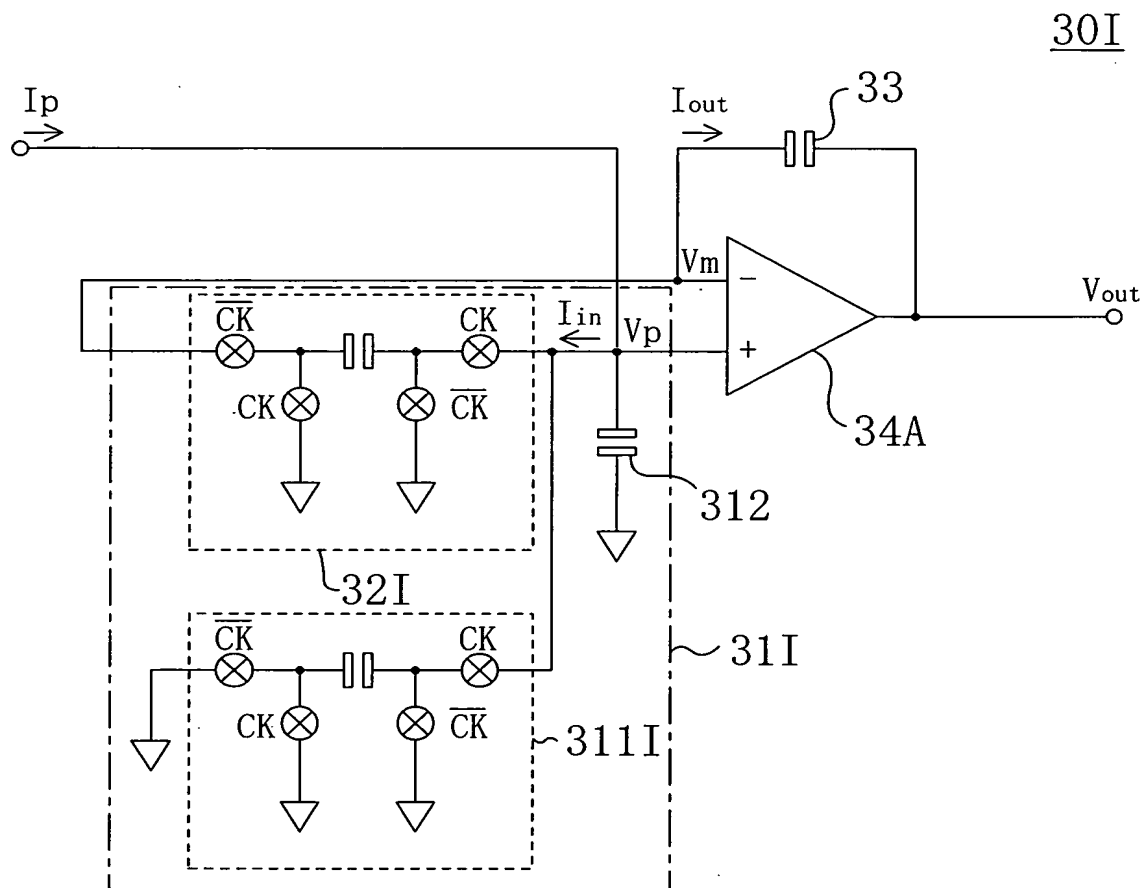


FIG. 19

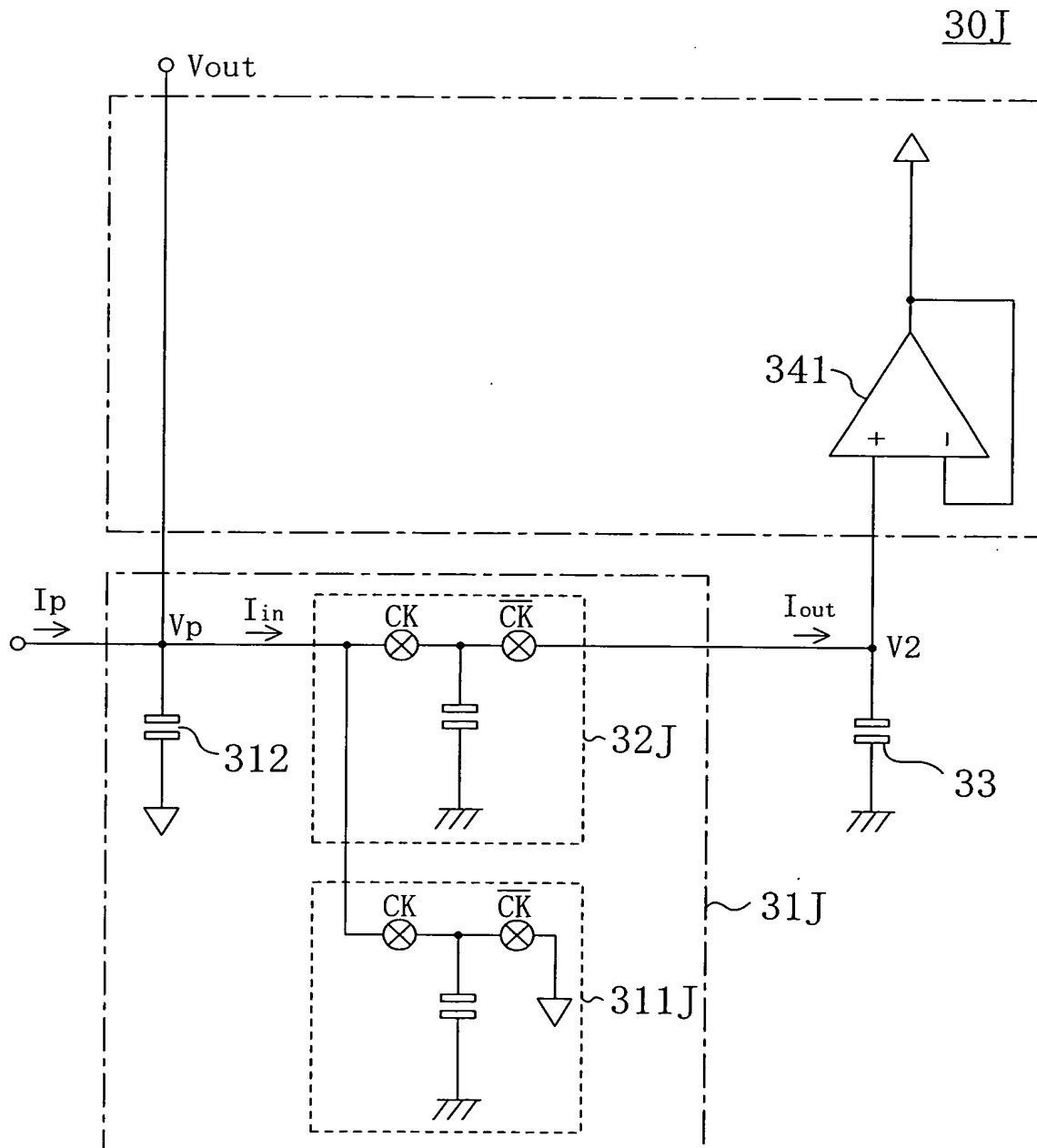


FIG. 20

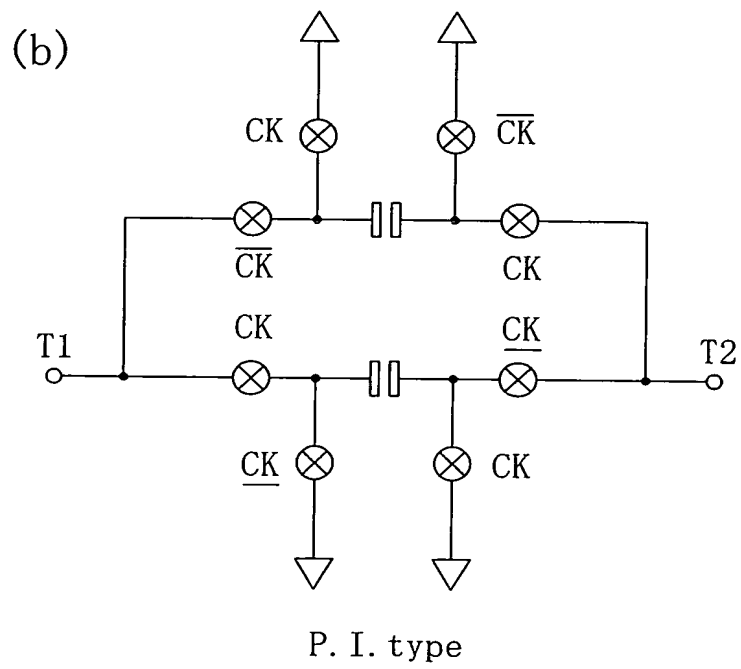
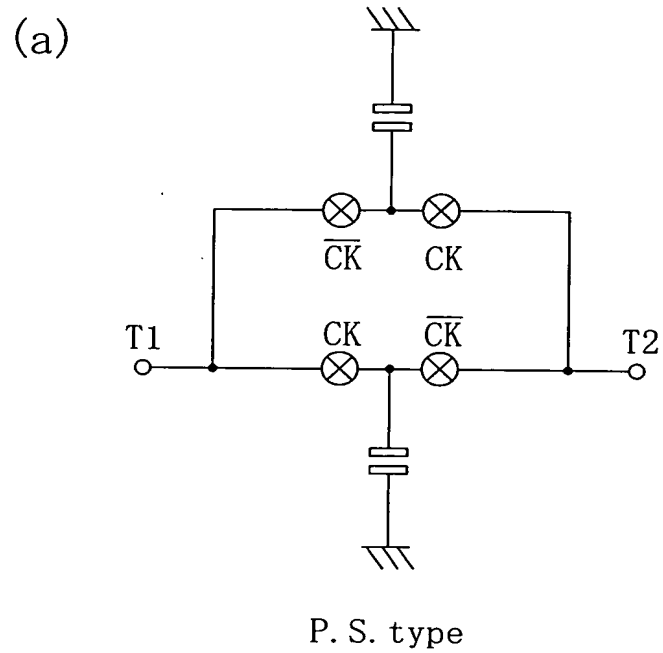


FIG. 21

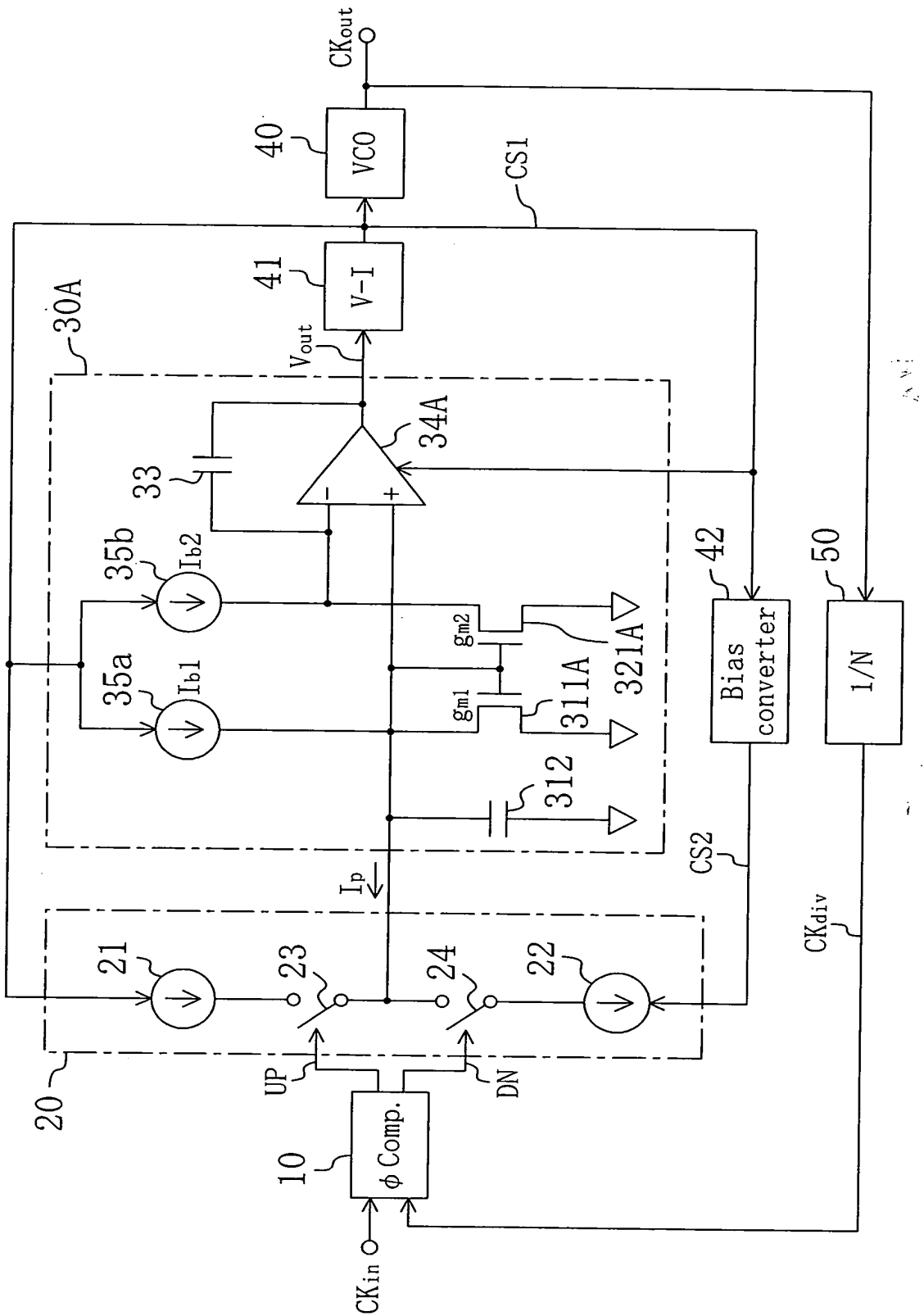


FIG. 22

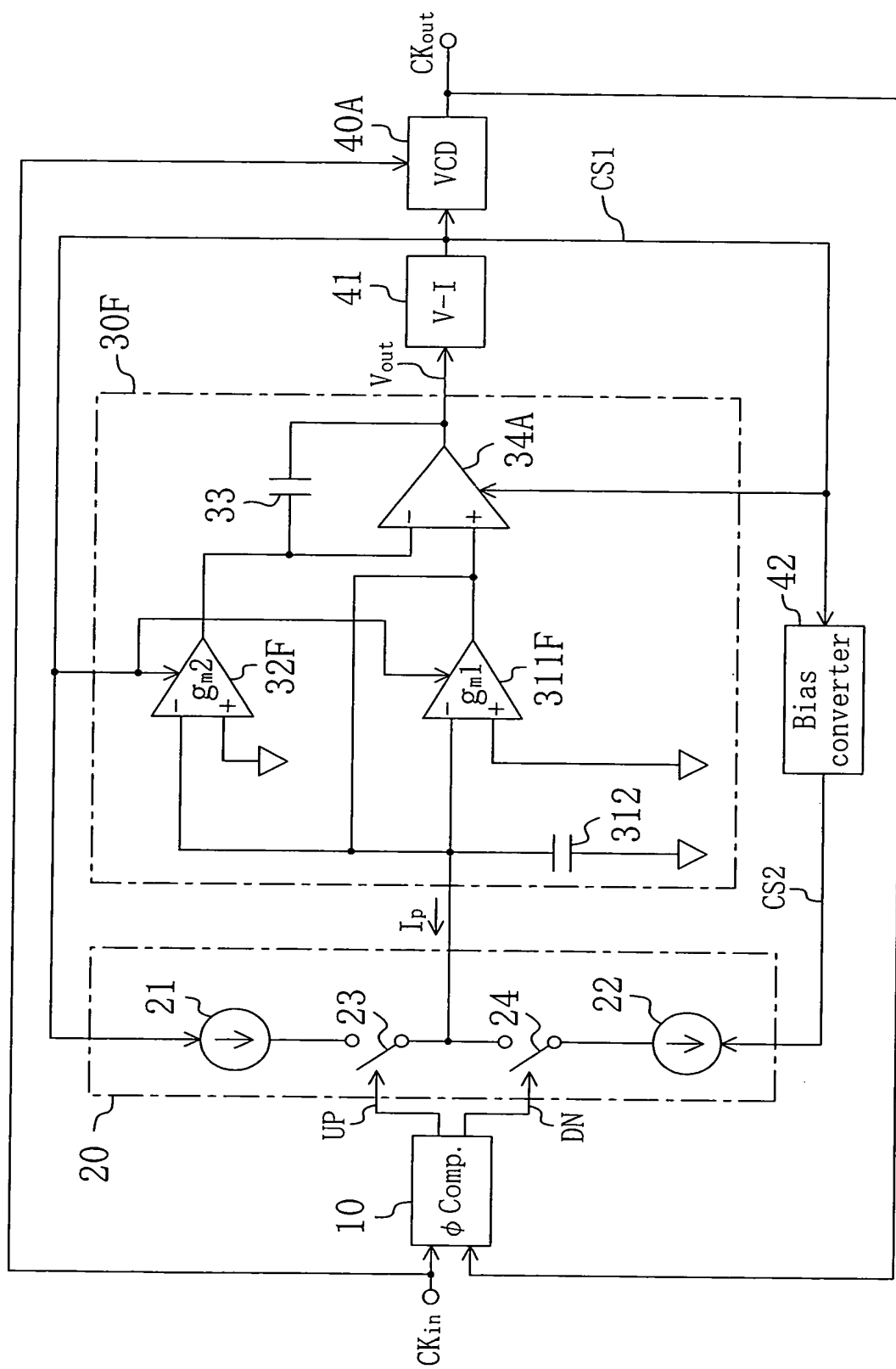


FIG. 23

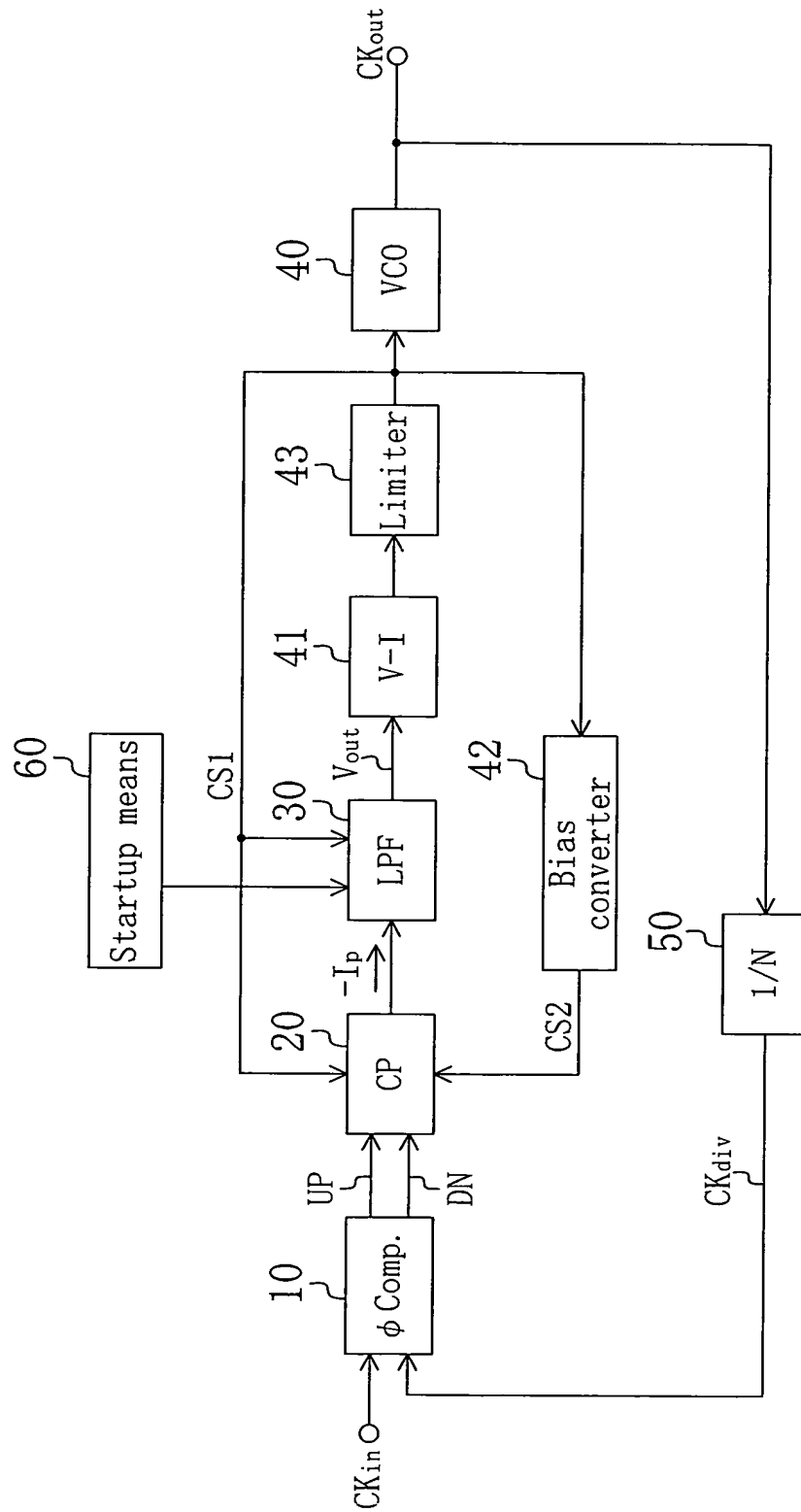


FIG. 24

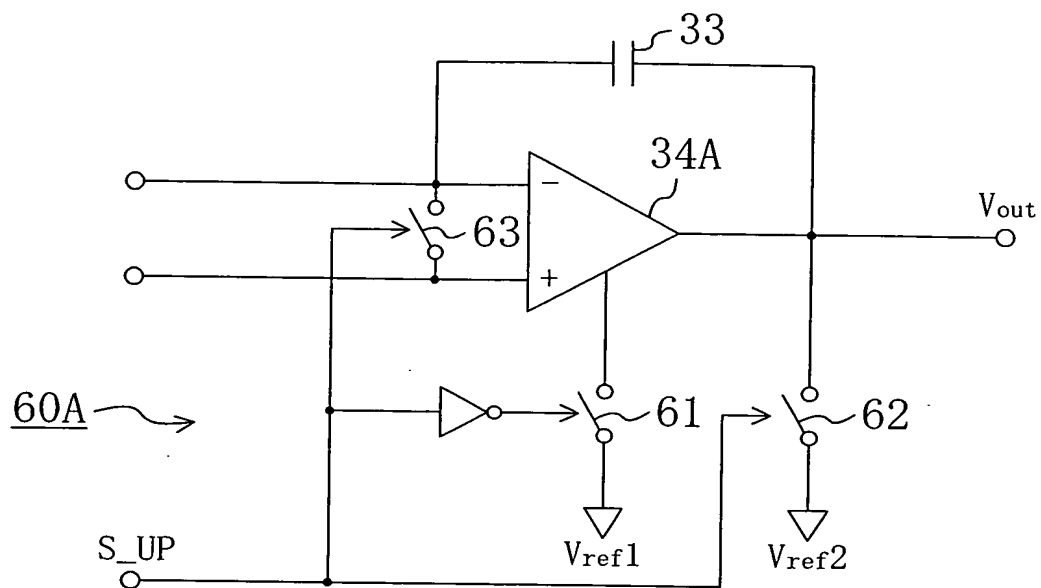


FIG. 25

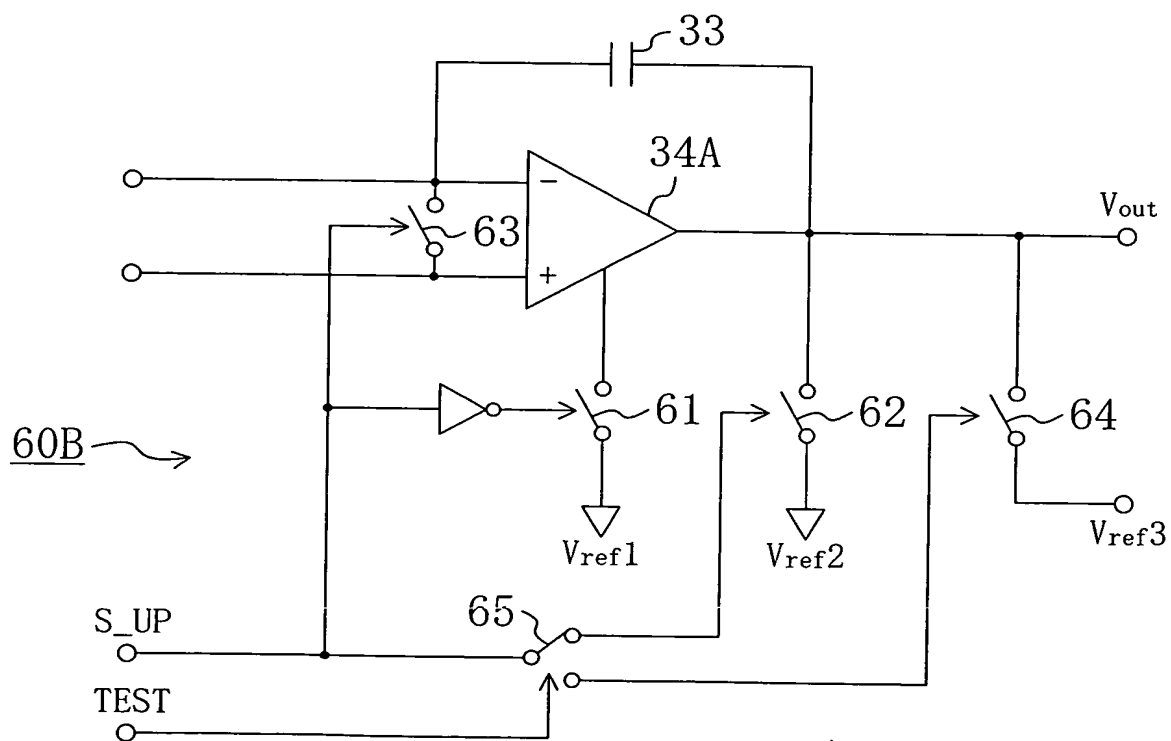


FIG. 26

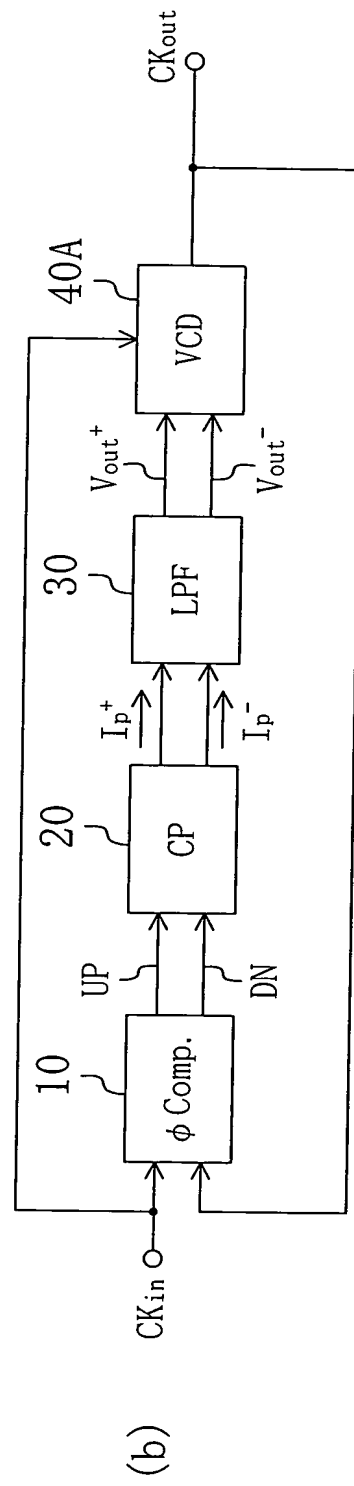
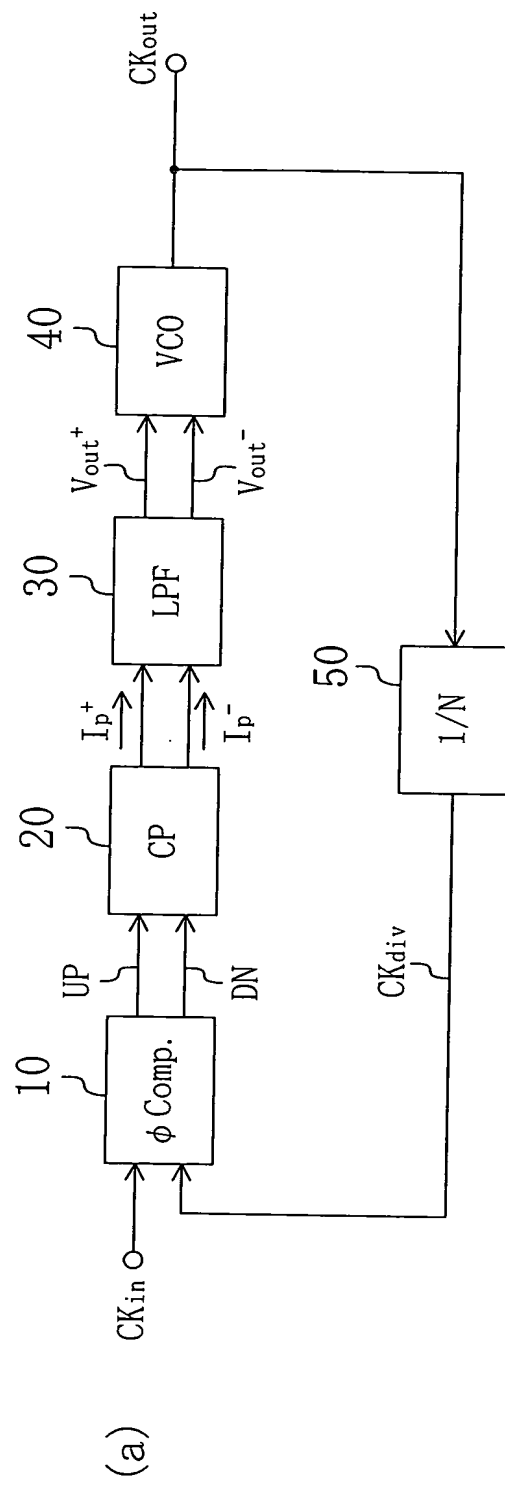




FIG. 27

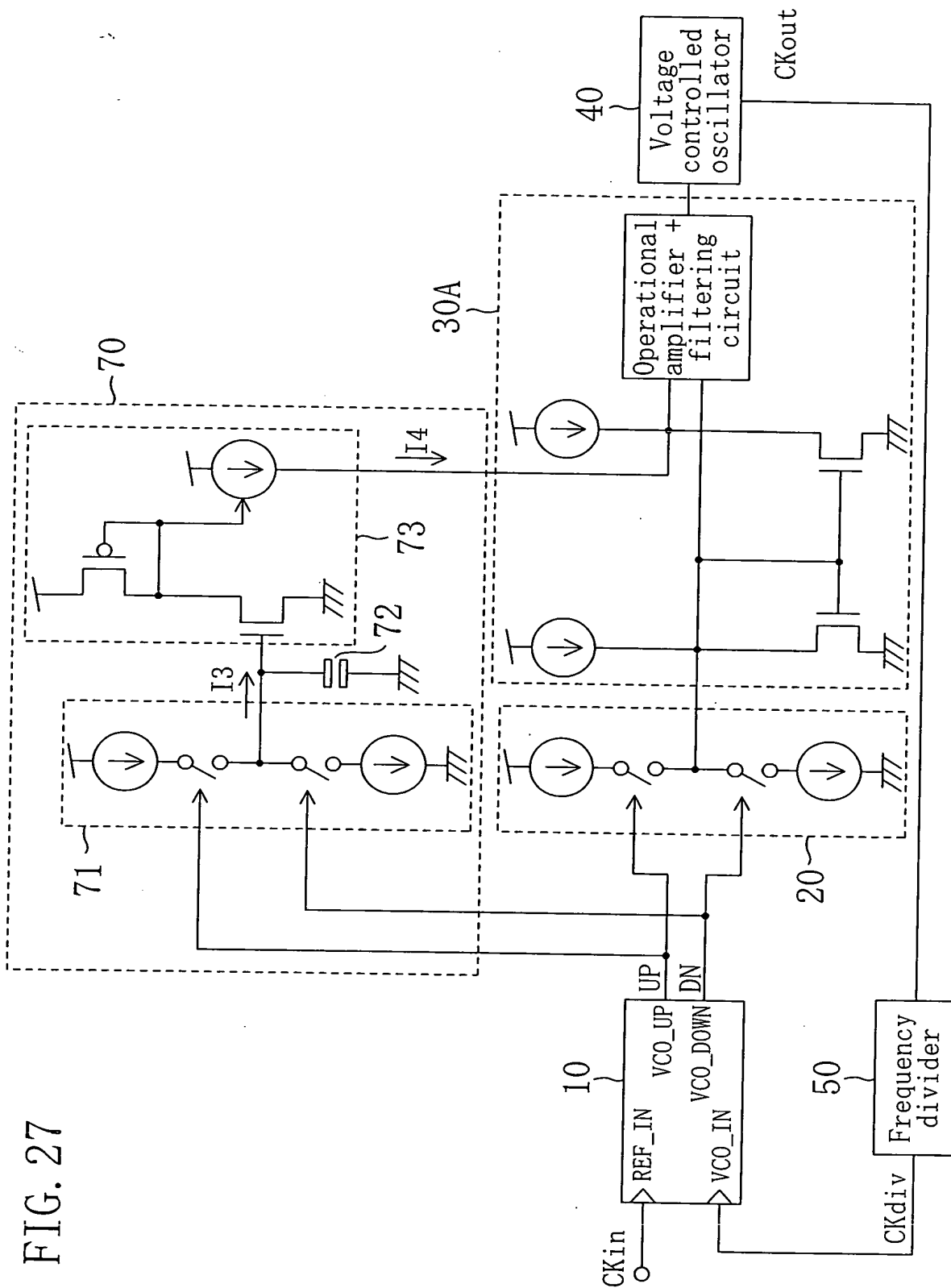
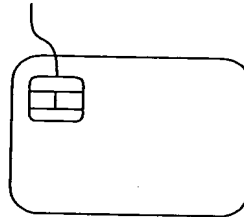


FIG. 28

LSI including PLL or DLL  
of this invention

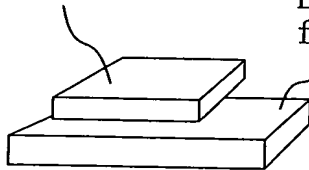


Exemplified  
application to IC card

FIG. 29

COC component  
including PLL or DLL  
of this invention

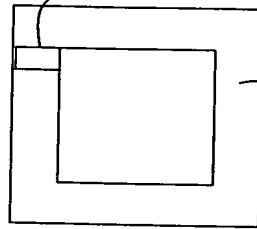
Base member  
for adhesion



Exemplified application  
to COC component

FIG. 30

PLL or DLL of  
this invention

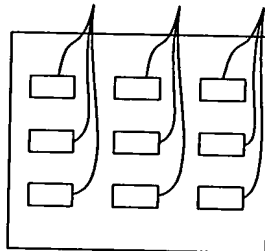


LSI pad region

Exemplified  
application to LSI pad

FIG. 31

PLL or DLL of this  
invention



Exemplified application  
to MPU clock

FIG. 32

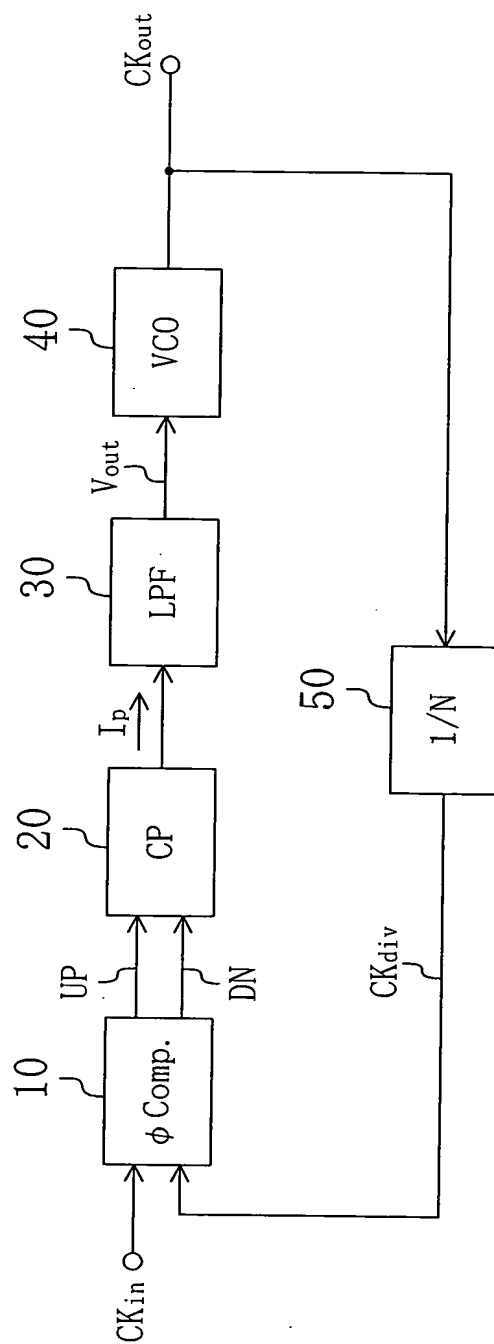


FIG. 33

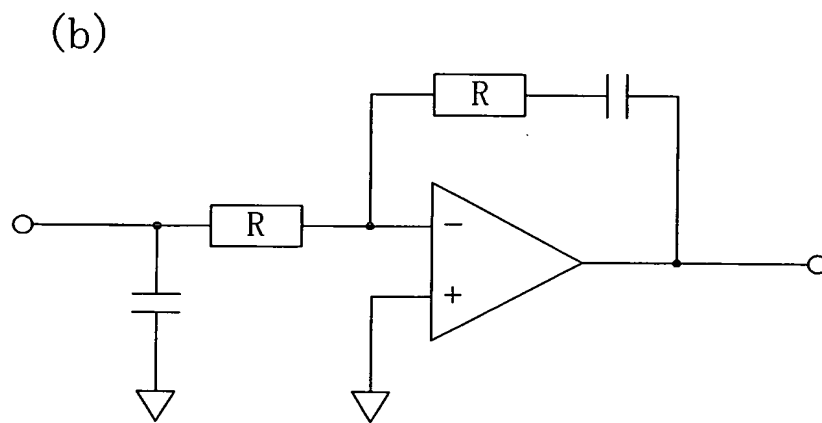
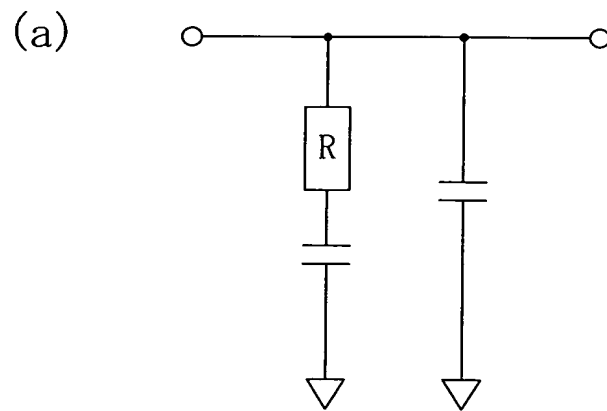


FIG. 34

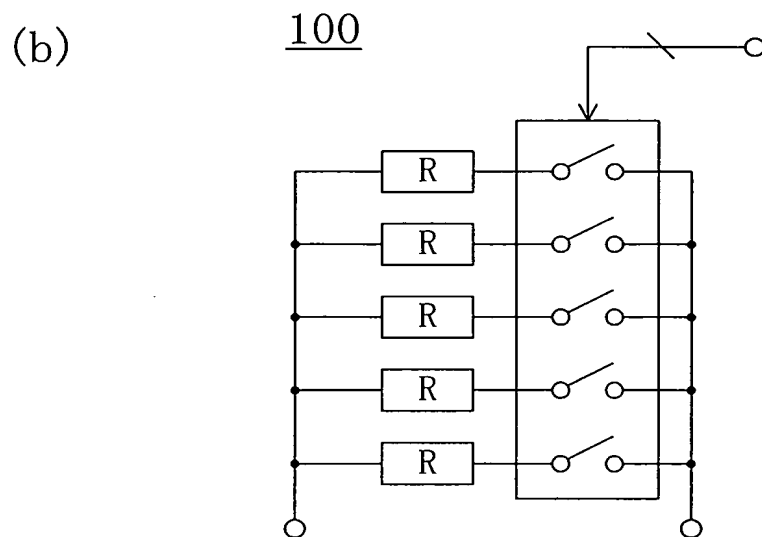
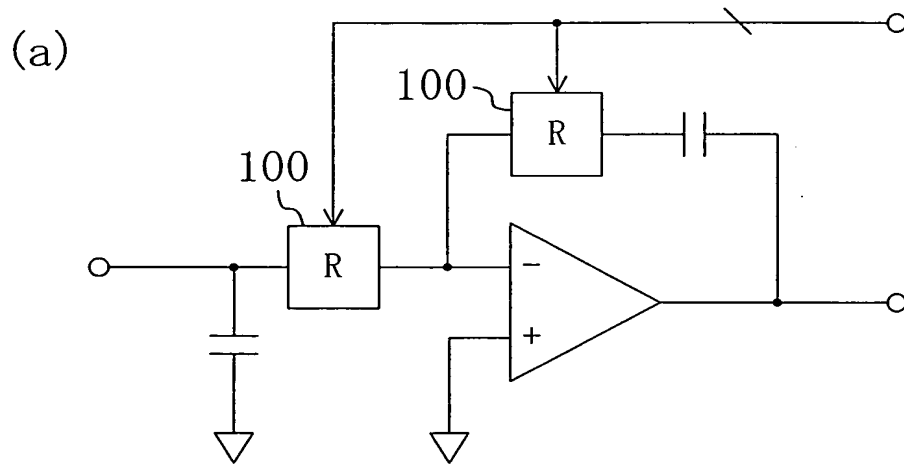


FIG. 35

